

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	2043	@ad<="20040301" and (257/717-718).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/27 09:03
S2	1319	@ad<="20040301" and (257/706).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 05:09
S3	714	@ad<="20040301" and (257/720).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 05:10
S4	812	@ad<="20040301" and (257/675).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 07:11
S5	147	@ad<="20040301" and (257/625).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/27 10:48
S6	163	@ad<="20040301" and (257/276).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 05:33
S7	625	@ad<="20040301" and (438/122).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 05:10
S8	1452	@ad<="20040301" and (174/16.3).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 05:10
S9	176	@ad<="20040301" and (228/222).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 05:11
S10	18	@ad<="20040301" and (361/274.3).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 05:11
S11	767	@ad<="20040301" and (361/697).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 07:07
S12	341	@ad<="20040301" and (361/702).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 05:11

S13	671	@ad<="20040301" and (361/709).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 05:12
S14	11	@ad<="20040301" and (361/514).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 05:12
S15	439	@ad<="20040301" and 'thermal' with 'electrical' and 'semiconductor body'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/28 15:11
S16	16	@ad<="20040301" and 'thermal' with 'electrical' and 'semiconductor body' and 'trough'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 05:36
S17	0	@ad<="20040301" and 'heat sink' same ('SiC' or 'diamond') and 'semiconductor body' and 'trough'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 05:37
S18	28	@ad<="20040301" and 'heat sink' same ('SiC' or 'diamond') and 'semiconductor body'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 05:45
S19	169	@ad<="20040301" and 'thermo-electrical'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/27 10:12
S20	22	@ad<="20040301" and 'thermo-electrical' and 'heat sink'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/27 10:13
S21	0	@ad<="20040301" and 'semiconductor boby' and 'heat sink' and 'conductive' and 'heat transfer' same 'helix'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 06:08
S22	0	@ad<="20040301" and 'semiconductor boby' and 'heat sink' and 'conductive' and 'heat transfer' same 'maze'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 06:07
S23	0	@ad<="20040301" and 'semiconductor boby' and 'heat sink' and 'conductive' and 'heat transfer'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 06:07
S24	0	@ad<="20040301" and 'semiconductor boby' and 'heat sink' and 'conductive'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 06:07
S26	5	@ad<="20040301" and 'semiconductor' and 'heat sink' and 'conductive' and 'heat transfer' same 'helix'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 06:09

S27	7	@ad<="20040301" and 'semiconductor' and 'heat sink' and 'conductive' and 'heat transfer' same 'maze'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 06:11
S28	4	@ad<="20040301" and 'heat regulating' and 'semiconductor' and 'heat sink'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 06:17
S29	0	@ad<="20040301" and 'heat regulating device' and 'IC' and 'heat sink'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 06:17
S30	0	@ad<="20040301" and 'heat regulating' and 'IC' and 'heat sink'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 06:18
S31	7	@ad<="20040301" and 'heat regulating' and 'chip' and 'heat sink'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 06:19
S32	0	@ad<="20040301" and 'heat regulating device' same 'maze'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 06:20
S33	0	@ad<="20040301" and 'heat regulating device' same 'helix'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 06:44
S34	55	@ad<="20040301" and 'heat sink' same 'helix'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 06:25
S35	8	@ad<="20040301" and 'heat sink' same 'maze'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 07:32
S36	9	@ad<="20040301" and 'heat sink' same 'helix' and 'semiconductor'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 06:25
S37	0	@ad<="20040301" and 'thermal' with 'regulating' same 'semiconducotr' same ('heat sink' or 'heat spreader')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 06:46
S38	0	@ad<="20040301" and 'thermal' with 'control' same 'semiconducotr' same ('heat sink' or 'heat spreader')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 06:46
S39	0	@ad<="20040301" and 'heat' with 'control' same 'semiconducotr' same ('heat sink' or 'heat spreader')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 06:46

S40	4	@ad<="20040301" and 'thermal' with 'regulating' same 'semiconductor' same ('heat sink' or 'heat spreader')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 06:46
S41	737	@ad<="20040301" and ('thermal' or 'heat') with ('regulating' or 'control') same 'semiconductor' same ('heat sink' or 'heat spreader')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 06:47
S42	220	@ad<="20040301" and ('thermal' or 'heat') with ('regulating' or 'control') same 'semiconductor device' same ('heat sink' or 'heat spreader')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 06:47
S43	145	@ad<="20040301" and ('thermal' or 'heat') with ('regulating' or 'control') same 'IC' same ('heat sink' or 'heat spreader')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 06:48
S44	424	@ad<="20040301" and ('thermal' or 'heat') with ('regulating' or 'control') same 'chip' same ('heat sink' or 'heat spreader')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 06:48
S45	1508	@ad<="20040301" and (361/695).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 07:21
S46	144	@ad<="20040301" and (361/696).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 07:07
S47	1	"6016250".PN.	USPAT; USOCR	OR	ON	2005/10/02 07:07
S48	1	"5773755".PN.	USPAT; USOCR	OR	ON	2005/10/02 07:07
S49	1	"5463529".PN.	USPAT; USOCR	OR	ON	2005/10/02 07:08
S51	181	@ad<="20040301" and ('array' or 'matrix') with 'heat sink' same 'semiconductor device'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 07:16
S52	24	@ad<="20040301" and 'matrix' with 'heat sink' same 'semiconductor device'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 07:20
S53	522	@ad<="20040301" and 'matrix' with 'heat sink'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 07:20

S54	394	@ad<="20040301" and (361/694).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 07:21
S55	1	"5988488".PN.	USPAT; USOCR	OR	ON	2005/10/02 07:26
S56	1	"5848467".PN.	USPAT; USOCR	OR	ON	2005/10/02 07:26
S57	1162	@ad<="20040301" and (257/718).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 07:28
S58	952	@ad<="20040301" and (257/717).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 07:28
S59	711	@ad<="20040301" and (257/718).ccls. and 'heat sink'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 07:28
S60	283	@ad<="20040301" and (257/718).ccls. and 'heat sink' same 'semiconductor'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 07:29
S61	5	@ad<="20040301" and 'maze' with 'heat sink'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 07:42
S62	20	@ad<="20040301" and 'helix' with 'heat sink'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 07:32
S63	35	@ad<="20040301" and 'thermal control' with 'IC'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/27 09:32
S64	1	"6016250".PN.	USPAT; USOCR	OR	ON	2005/10/02 07:47
S65	943	@ad<="20040301" and (257/719).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/27 09:08
S67	1	@ad<="20040301" and (257/719).ccls. and 'heat' same dissipat\$4 same 'silicon carbide'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/27 09:06
S68	32	@ad<="20040301" and (257/719).ccls. and 'diamond'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/27 09:16

S71	1	@ad<="20040301" and 'therm' with 'sensor' and ('diamond' or 'silicon carbide')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/27 09:19
S75	45	@ad<="20040301" and 'semiconductor' and ('thermal' or 'thermo') with 'electrical' same 'heat flow' and ('diamond' or 'silicon carbide')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/27 09:22
S76	1	"5712448".PN.	USPAT; USOCR	OR	ON	2005/12/27 09:26
S77	1	"5705770".PN.	USPAT; USOCR	OR	ON	2005/12/27 09:26
S78	143	@ad<="20040301" and 'thermal control' with 'semiconductor'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/08 12:09
S79	35	@ad<="20040301" and 'thermal control' with 'ic'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/27 09:35
S80	2	@ad<="20040301" and 'Controlling hot spots' and ('diamond' or 'silicon carbide')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/27 09:36
S81	124	@ad<="20040301" and 'semiconductor' same 'hot spots' and ('diamond' or 'silicon carbide')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/27 09:49
S82	1	"6521991".PN.	USPAT; USOCR	OR	ON	2005/12/27 09:39
S83	1	"6334311".PN.	USPAT; USOCR	OR	ON	2005/12/27 09:40
S84	1	"6322626".PN.	USPAT; USOCR	OR	ON	2005/12/27 09:41
S85	1	"6199927".PN.	USPAT; USOCR	OR	ON	2005/12/27 09:41
S86	13	@ad<="20040301" and 'semiconductor' same 'hot spots' same ('diamond' or 'silicon carbide')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/27 10:08
S87	2	@ad<="20040301" and 'semiconductor' same 'thermo-electric' same ('diamond' or 'silicon carbide')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/27 10:09
S88	141	@ad<="20040301" and 'semiconductor' and 'thermo-electric' and ('diamond' or 'silicon carbide')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/27 10:10

S89	7	@ad<="20040301" and 'semiconductor' and 'thermo-electric' same ('diamond' or 'silicon carbide')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/27 10:10
S90	12	@ad<="20040301" and 'semiconductor' same 'thermo-electric' and ('diamond' or 'silicon carbide')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/27 10:11
S91	171	@ad<="20040301" and 'thermo-electrical'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/27 10:12
S92	23	@ad<="20040301" and 'thermo-electrical' and 'heat sink'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/27 10:14
S93	776	@ad<="20040301" and 'thermo' with electric\$2 and 'heat sink'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/27 10:13
S94	501	@ad<="20040301" and 'thermo-electric' and 'heat sink'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/27 10:34
S95	1	@ad<="20040301" and 'thermo-electric' and 'heat sink' same 'silicon carbide'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/27 10:14
S96	27	@ad<="20040301" and 'thermo-electric' and 'heat sink' and 'silicon carbide'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/27 10:26
S97	74	@ad<="20040301" and 'thermo-electric' and 'heat sink' and ('silicon carbide' or 'diamond')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/27 10:26
S98	9	@ad<="20040301" and 'thermo-electric' and 'heat sink' same 'diamond'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/27 10:30
S99	1	@ad<="20040301" and 'thermo-electric' and 'heat sink' same 'carbide'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/27 10:35
S100	27	@ad<="20040301" and 'thermo-electric' and 'heat sink' and 'silicon carbide'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/27 10:45
S101	4	(("6098408") or ("5940784")). PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/27 10:45

S102	1	"5940784".PN.	USPAT; USOCR	OR	ON	2005/12/27 10:47
S103	1	"5867990".PN.	USPAT; USOCR	OR	ON	2005/12/27 10:47
S104	410	@ad<="20040301" and (62/3.7).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/27 10:48
S105	1	"5822993".PN.	USPAT; USOCR	OR	ON	2005/12/27 10:48
S106	1	"5867990".PN.	USPAT; USOCR	OR	ON	2005/12/27 10:48
S107	1	"5690849".PN.	USPAT; USOCR	OR	ON	2005/12/27 10:49
S108	432	@ad<="20040301" and ("SiC" or diamond) with therm\$2 with electrical and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/28 15:25
S109	0	@ad<="20040301" and ("SiC" or diamond) with "thermo-electrical" and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/28 15:13
S110	0	@ad<="20040301" and ("SiC" or diamond) with "thermo-electrical"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/28 15:13
S111	171	@ad<="20040301" and "thermo-electrical"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/28 15:47
S112	33	@ad<="20040301" and "thermo-electrical" and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/28 15:15
S114	37	@ad<="20040301" and "thermo-electrical" and (semiconductor or "IC")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/28 15:18
S115	1	ANTONOVSKA	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/28 15:21
S117	285	@ad<="20040301" and ("SiC" or diamond) with therm\$2 with electric\$2 and semiconductor and cool\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/28 15:25
S118	100	@ad<="20040301" and ("SiC" or diamond) with therm\$2 with electric\$2 and (semiconductor or "IC") same cool\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/28 15:28

S119	26	@ad<="20040301" and ("SiC" or diamond) with ("therm\$2 with electric\$2" or thermoelectric or "thermo-electrical") and (semiconductor or "IC") same cool\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/28 15:46
S120	2237	@ad<="20040301" and (62/259.2)".ccls" or (62/3.7).ccls. or (62/3.2).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/28 15:46
S121	67	@ad<="20040301" and ("thermo-electrical" or themoelectric) same cool\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/28 15:48
S124	109	@ad<="20040301" and ("thermo-electrical" or thermoelectric) same cool\$3 same "IC"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/17 17:21
S125	8	(("6,196,002") or ("5,569,950") or ("5,032,897") or ("6,094,919")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/04/28 16:10
S126	1	"6222113".PN.	USPAT; USOCR	OR	ON	2006/04/28 16:12
S127	1	"6121539".PN.	USPAT; USOCR	OR	ON	2006/04/28 16:12
S128	1	"5956569".PN.	USPAT; USOCR	OR	ON	2006/04/28 16:13
S129	99	@ad<="20040301" and ("thermo-electrical" or thermoelectric or "thermo-electric") with (diamond or SiC)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/30 07:43
S130	0	@ad<="20040301" and ("thermo-electrical" or thermoelectric or "thermo-electric") with "coil structure"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/30 07:15
S131	394	@ad<="20040301" and ("thermo-electrical" or thermoelectric or "thermo-electric") with coil	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/30 07:16
S133	20	@ad<="20040301" and "semiconductor" same ("thermo-electrical" or thermoelectric or "thermo-electric") with coil	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/30 07:16
S135	20	@ad<="20040301" and "semiconductor" same ("thermo-electrical" or thermoelectric or "thermo-electric") with (coil or maze)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/30 07:16

S136	19729	@ad<="20040301" and wafer with semiconductor with "integrated circuit"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/30 07:46
S137	1	@ad<="20040301" and thermoelectric same wafer with semiconductor with "integrated circuit"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/30 07:44
S138	6	@ad<="20040301" and cooler same wafer with semiconductor with "integrated circuit"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/30 07:46
S139	18	("5689957" "5689958" "5690849" "5822993" "5867990" "5940784").PN. OR ("6098408").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/09/08 11:26
S140	2428	@ad<="20040301" and cool\$4 same uniform\$3 same temperature same gradient	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/08 12:11
S141	552	@ad<="20040301" and cool\$4 with uniform\$3 with temperature with gradient	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/08 12:11
S142	1	@ad<="20040301" and (integrated or "IC") same cool \$4 with uniform\$3 with temperature with gradient	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/08 12:12
S143	13	@ad<="20040301" and (die or chip or "IC") same cool\$4 with uniform\$3 with temperature with gradient	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/08 12:56
S144	124	@ad<="20040301" and (semiconductor) same cool\$4 same uniform\$3 same temperature same gradient	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/08 12:57
S145	101	@ad<="20040301" and (semiconductor) same cool\$4 same uniform\$3 same temperature with gradient	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/08 13:03
S146	54	@ad<="20040301" and (semiconductor) same uniform \$3 with cool\$3 same temperature same gradient	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/08 13:15
S147	21	("4582985" "4935864" "5444637" "5894056" "5918469" "5940784" "6028263" "6080969" "6088662").PN. OR ("6230497").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/09/08 13:14
S148	404	@ad<="20040301" and (semiconductor) same uniform \$3 with cool\$3 with temperature	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/08 13:16

S149	86	@ad<="20040301" and "semiconductor device" same uniform\$3 with cool\$3 with temperature	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/08 13:35
S150	38	@ad<="20040301" and "thermoelectric" same "uniform temperature" same distribution	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/17 18:20
S151	36	@ad<="20040301" and "thermoelectric" same "uniform temperature" with distribution	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/08 13:36
S152	13	("5040381" "5229327" "5233622" "5637921" "5712448" "5724818" "5867990" "5874775" "5956569" "5966941" "6000225" "6121539" "6222113").PN. OR ("6893902").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/09/08 13:38
S153	67	@ad<="20040301" and spiral with "thermoelectric"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/17 15:44
S154	0	@ad<="20040301" and "spiral or coil" with "thermoelectric"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/17 15:45
S155	419	@ad<="20040301" and (spiral or coil) with "thermoelectric"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/17 15:46
S156	365	@ad<="20040301" and coil with "thermoelectric"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/17 15:46
S157	2	"20060054091"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/17 16:37
S158	2	("6882543").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/01/17 16:38
S159	2	("6804966").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/01/17 16:39
S160	55	@ad<="20040301" and "thermoelectric module" same "temperature" same distribution	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/17 16:49

S161	158	@ad<="20040301" and "thermoelectric" same "uniform temperature"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/17 16:45
S162	64	@ad<="20040301" and "thermoelectric" with "uniform temperature"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/17 16:45
S164	62	@ad<="20040301" and "thermoelectric module" same coil	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/17 17:00
S165	2	("6154266").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/01/17 17:00
S166	41	("20010052234" "20020053359" "20020069906" "20020139123" "3136134" "3296034" "3607444" "3663307" "4443650" "5006178" "5254178" "5430322" "5837929" "5865975" "5869242" "5874219" "5900071" "5922988" "6060331" "6060657" "6062681" "6071351" "6072925" "6084050" "6094919" "6154266" "6154479" "6180351" "6271459" "6282907" "6300150" "6365821" "6384312" "6403876" "6410971" "6412286" "6505468" "6605772" "6696635").PN. OR ("7164077").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/01/17 17:03
S167	797	@ad<="20040301" and ("thermo-electrical" or thermoelectric) same cool\$3 same ("IC" or die or chip)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/17 17:23
S168	513	@ad<="20040301" and ("thermo-electrical" or thermoelectric) same cool\$3 with ("IC" or die or chip)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/17 17:23
S169	455	@ad<="20040301" and ("thermo-electrical" or thermoelectric) with cool\$3 with ("IC" or die or chip)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/17 17:31

S170	457	@ad<="20040301" and ("thermo-electrical" or thermoelectric or thermoelement) with cool\$3 with ("IC" or die or chip)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/17 17:54
S171	55	@ad<="20040301" and ("thermo-electrical" or thermoelectric or thermoelement) with cool\$3 with ("IC" or die or chip) and (grid or maze)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/17 17:47
S172	77	@ad<="20040301" and thermoelement same (grid or maze or coil)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/17 17:47
S173	50	@ad<="20040301" and thermoelement with (grid or maze or coil)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/17 17:47
S174	1469	@ad<="20040301" and ("thermo-electrical" or thermoelectric or thermoelement) same arrangement	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/17 17:55
S175	283	@ad<="20040301" and ("thermo-electrical" or thermoelectric or thermoelement) same arrangement and cool\$3 and chip	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/17 18:05
S176	77	@ad<="20040301" and spiral with ("thermo-electrical" or thermoelectric or thermoelement or "TEC")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/17 18:20
S177	44	@ad<="20040301" and ("thermoelectric" or "TEC") same "uniform temperature" same distribution	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/17 18:26
S178	46	@ad<="20040301" and ("thermoelectric" or "TEC" or thermoelement) same "uniform temperature" same distribution	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/17 18:21
S179	461	@ad<="20040301" and ("thermoelectric" or "TEC") with pattern	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/17 18:27
S180	8	@ad<="20040301" and ("thermoelectric" or "TEC") with pattern same "uniform temperature"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/17 18:31

S181	2	("6,952,036").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/08/20 11:32
S182	2	"20040129937"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/20 11:33
S183	0	@ad<="20051223" and "top gate" with ("TFT" or "thin film transistor") with polymer with polysiloxane	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/20 11:40
S184	1	@ad<="20051223" and "top gate" with ("TFT" or "thin film transistor") same polysiloxane	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/20 11:48
S185	49	@ad<="20051223" and ("TFT" or "thin film transistor") same polysiloxane	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/20 11:48
S186	219	@ad<="20051223" and ("TFT" or "thin film transistor") same (polysiloxane or polystyrene or polysilsesquioxane)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/20 11:49
S187	85	@ad<="20051223" and ("TFT" or "thin film transistor") with (polysiloxane or polystyrene or polysilsesquioxane)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/20 11:50
S188	8	("5981970" "6232157" "6558987" "6563174" "6617609" "6768132").PN. OR ("7005674").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/08/20 12:04
S189	8	("20020155729" "20030183915" "20040077122" "5705826" "6734038" "6740900").PN. OR ("6913944").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/08/20 12:10
S191	354	@ad<="20051223" and (257/40).ccls. and organic with TFT	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/20 12:46
S192	194	@ad<="20040301" and ("SiC" or diamond) with ("thermo-electrical" or "thermo-electrical" or thermoelectric or "thermoelement" or "TE") and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/20 13:23
S193	968	@ad<="20040301" and ("thermo-electrical" or "thermo-electrical" or thermoelectric or "thermoelement" or "TE") with coil	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/20 13:29

S194	25	@ad<="20040301" and ("thermo-electrical" or "thermo-electrical" or thermoelectric or "thermoelement" or "TE") with coil same semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/20 13:29
S195	125	@ad<="20040301" and ("thermo-electrical" or "thermo-electrical" or thermoelectric or "thermoelement" or "TE") same arrangement same shape	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/20 13:32
S196	39	@ad<="20040301" and "thermoelectric" same "uniform temperature" same distribution	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/20 13:55
S197	34	("3733887" "4119403" "4320626" "4402185" "4491173" "4584061" "5088006" "5097207" "5115858" "5177878" "5203401" "5267607" "5469708" "5491452").PN. OR ("5740016").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/08/20 14:02
S199	1936	@ad<="20040301" and ("thermo-electrical" or "thermo-electrical" or thermoelectric or "thermo-electric" or thermoelement or "TE") same uniform	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/20 14:11
S200	664	@ad<="20040301" and ("thermo-electrical" or "thermo-electrical" or thermoelectric or "thermo-electric" or thermoelement or "TE") same uniform same temperature	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/20 14:12
S201	2315	@ad<="20040301" and ("thermo-electrical" or "thermo-electrical" or thermoelectric or "thermo-electric" or thermoelement or "TE") same coil	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/24 14:05
S202	503	@ad<="20040301" and ("thermo-electrical" or "thermo-electrical" or thermoelectric or "thermo-electric" or thermoelement or "TE") same spiral	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/24 14:07
S203	2890	@ad<="20040301" and ("thermo-electrical" or "thermo-electrical" or thermoelectric or "thermo-electric" or thermoelement or "TE") same pattern	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/24 14:08

S204	17	("3635037" "3681929" "3779814" "4065936" "4730459" "5228923" "5232516" "5592363" "5802856" "6084172" "6096966" "6334311" "6347521").PN. OR ("6672076").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/10/24 14:11
S205	1004	@ad<="20040301" and ("thermo-electrical" or "thermo-electrical" or thermoelectric or "thermo-electric" or thermoelement or "TE") with coil	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/24 14:13
S206	1383	@ad<="20040301" and ("thermo-electrical" or "thermo-electrical" or thermoelectric or "thermo-electric" or thermoelement or "TE") with pattern	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/24 14:13
S207	17	@ad<="20040301" and ("thermo-electrical" or "thermo-electrical" or thermoelectric or "thermo-electric" or thermoelement or "TE") with coil with densities	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/24 14:15
S208	2	("5740016").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/24 14:18
S209	1391	@ad<="20040301" and ("thermo-electrical" or "thermo-electrical" or thermoelectric or "thermo-electric" or thermoelement or "TE") with densities	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/24 14:20
S210	28	@ad<="20040301" and ("thermo-electrical" or "thermo-electrical" or thermoelectric or "thermo-electric" or thermoelement or "TE") same densities with pattern	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/24 14:21
S211	1530	@ad<="20040301" and ("thermo-electrical" or "thermo-electrical" or thermoelectric or "thermo-electric" or thermoelement or "TE") with arrangement	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/24 14:23
S212	123	@ad<="20040301" and (thermoelectric or "thermo-electric") same spiral	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/24 14:24

S213	779	@ad<="20040301" and (thermoelectric or "thermo-electric") same coil	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/24 14:30
S214	800	@ad<="20040301" and (thermoelectric or "thermo-electric") same densities	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/24 14:30
S215	17	@ad<="20040301" and (thermoelectric or "thermo-electric") same coil with arrangement	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/24 14:30
S216	6	@ad<="20040301" and (thermoelectric or "thermo-electric") same densities with pattern	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/24 14:30
S217	18	@ad<="20040301" and (thermoelectric or "thermo-electric") same different with densities	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/24 15:13
S218	29	@ad<="20040301" and (thermoelectric or "thermo-electric" or peltier) same different with densities	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/24 16:17
S219	1	@ad<="20040301" and (thermoelectric or "thermo-electric" or peltier) same different with densities with arrangement	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/24 16:17
S220	9	("5715684" "6000225" "6230497" "6250085" "6282907" "6396700" "6424533" "6489551" "6548894").PN. OR ("6804966").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/10/24 16:18
S221	14	("20020005522" "20020024154" "5168339" "5216887" "5430322" "5439528" "5441576" "5892656" "5950067" "5952728" "6111513" "6306673" "6347661" "6400013").PN. OR ("6573596").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/10/24 16:22
S222	37	("3159979" "3879229" "4095998" "4362023" "4453385" "4463569" "4673863" "5361587" "5385022" "5448891" "5465578" "5605048").PN. OR ("6000225").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/10/24 16:24

S224	475	@ad<="20040301" and peltier same coil	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/24 16:28
S225	15	@ad<="20040301" and peltier same coil with arrangement	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/24 16:29
S227	5053	@ad<="20040301" and (thermoelectric or peltier) with modules	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/25 09:02
S228	2158	@ad<="20040301" and "thermoelectric modules"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/25 09:02
S229	2	("6,498,382").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/25 09:07
S230	97	@ad<="20040301" and "thermoelectric modules" with arrangement	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/25 09:28
S231	57	@ad<="20040301" and "thermoelectric module" same "temperature" same distribution	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/25 09:47
S232	113	@ad<="20040301" and "thermoelectric modules" with array	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/25 09:49
S233	9	("5715684" "6000225" "6230497" "6250085" "6282907" "6396700" "6424533" "6489551" "6548894").PN. OR ("6804966").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/10/25 09:49
S234	32	("4420364" "4735847" "5588300" "5605048" "5737923" "5802856" "5956569" "6000225" "6096965").PN. OR ("6347521").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/10/25 09:51
S235	31	("20020014261" "3635037" "3681929" "3779814" "4065936" "4730459" "5092129" "5228923" "5232516" "5592363" "5802856" "6084172" "6096966" "6334311" "6346668" "6347521").PN. OR ("6598405").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/10/25 10:01

S236	28	@ad<="20040301" and "thermoelectric modules" with ring	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/25 10:15
S237	45	@ad<="20040301" and "thermoelectric modules" with pattern	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/25 10:16
S238	35	("3733887" "4119403" "4320626" "4402185" "4491173" "4584061" "5088006" "5097207" "5115858" "5177878" "5203401" "5267607" "5469708" "5491452").PN. OR ("5740016").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/10/25 10:18
S239	318	@ad<="20040301" and (thermoelectric or "TE" or peltier) same concentric	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/25 10:45
S240	3	("7015120").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/25 10:47
S241	268	@ad<="20040301" and (257/E23.082).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/30 10:24
S242	22	("3097027" "4092614" "4211888" "5022928" "5051865" "5061987" "5229327" "5598031" "5714791" "5724818" "5793107" "5837929" "5956569" "6080608" "6121661" "6162659" "6166411" "6196002").PN. OR ("6727422").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/10/30 10:39
S243	2159	@ad<="20040301" and "thermoelectric modules"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/30 11:07
S244	12	@ad<="20040301" and "thermoelectric modules" same concentric	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/30 11:07
S245	0	@ad<="20040301" and "thermoelectric modules" same "non-concentric"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/30 11:08

S246	3	@ad<="20040301" and "thermoelectric modules" same dense	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/30 11:10
S247	58	@ad<="20040301" and "thermoelectric modules" same dens\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/30 11:10
S248	23	@ad<="20040301" and "thermoelectric modules" same interval	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/30 11:12
S249	7	@ad<="20040301" and "thermoelectric" same dens\$3 with center	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/30 11:16
S250	369	@ad<="20040301" and "thermoelectric" with coil	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/30 11:23
S251	436	@ad<="20040301" and "thermoelectric" with distribut\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/30 11:23
S252	3	@ad<="20040301" and "thermoelectric" same coil with distribution	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/30 11:24
S253	2	("7231772").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/30 12:35
S254	93	("20020014261" "20020139123" "20020148234" "20030079770" "20030094265" "2944404" "2949014" "3004393" "3006979" "3071495" "3126116" "3129116" "3178895" "3213630" "3527621" "3607444" "3626704" "3635037" "3663307" "3681929" "3779814" "3817043" "4038831" "4065936" "4281516" "4297841" "4420940" "4494380" "4499329" "4730459" "4731338" "4905475" "4989626" "5038569" "5092129" "5097829" "5193347" "5228923" "5232516" "5385020" "5429680" "5499504"	US-PGPUB; USPAT; USOCR	OR	ON	2007/10/30 12:38

		"5584183" "5592363" "5605047" "5682748" "5802856" "5860472" "5867990" "5900071" "5921088" "5966941" "5987890" "6000225" "6082445" "6084172" "6096966" "6282907" "6319744" "6334311" "6346668" "6347521" "6359725" "6366832" "6367261" "6401462" "6412287" "6446442" "6477844" "6481213" "6510696" "6530231" "6530842" "6539725" "6560968" "6598405" "6625990" "6637210" "6672076" "6812395" "PCTUS2004026757" "PCTUS203772" "PCTUS324899" "PCTUS4026560" "RE36242" "RE38128").PN. OR ("7231772").URPN.				
S255	11	BSST and thermoelectric	US-PGPUB; USPAT; USOCR	OR	ON	2007/10/30 12:46
S256	291	@ad<="20040301" and "thermoelectric" same "temperature" same distribution	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/30 12:53
S257	16	dhindsa and thermoelectric	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/30 12:54
S258	35	("3733887" "4119403" "4320626" "4402185" "4491173" "4584061" "5088006" "5097207" "5115858" "5177878" "5203401" "5267607" "5469708" "5491452").PN. OR ("5740016").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/10/30 12:56
S259	2	"20070128954"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/30 13:24
S260	622	("pixel" with "image sensor") same (driv\$3 with control)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/30 14:24
S261	0	("pixel" with "image sensor") same (driv\$3 with control) same "gate contact"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/30 14:25

S262	2	("7217601").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/30 14:30
S263	2	("6727422").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/30 15:32
S264	2	("7231772").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/30 15:40
S265	2	("6573596").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/30 15:41

10/31/07 6:25:33 AM

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